



Device = VS1011E/LSR-ROHS
Package = 48L LQFP 7x7x1.4 mm
REF DOC = BF38137 REV C

Document: A
 Rev: 2.0
 Marking on device:

VS1011E
PPPPPPPPPP
YYWW R

where, P P P P P P P P P P = Lot ID
 YYWW = assembly Year and Week > 0925

R is a fixed character, short name of RoHS compliant package.

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip	14.455	Silicon	7440-21-3	100.00	14.455	7.798	77977.614
2	Lead Frame	Spot Ag Copper (Olin C7025)	79.408	Copper	7440-50-8	96.200	74.834	40.369	403692.510
				Ni	7440-02-0	3.000	2.334	1.259	12589.164
				Si	7440-21-3	0.650	0.506	0.273	2727.652
				Mg	7439-95-4	0.150	0.117	0.063	629.458
				Silver	7440-22-4		1.618	0.873	8728.314
3	Mold Compound	G700LX	86.394	Silica Fused	60676-86-0	81.500	70.411	37.983	379833.302
				Epoxy Resin	Trade Secret	10.000	8.639	4.661	46605.313
				Phenol Resin	Trade Secret	8.000	6.912	3.728	37284.251
				Carbon Black	1333-86-4	0.500	0.432	0.233	2330.266
4	Gold Wire	Gold (1.0 mils)	0.640	Au	7440-57-5	99.990	0.640	0.345	3452.140
				Dopant	-	0.010	0.000	0.000	0.345
5	Die Attach Material	CRM 1076 NS	1.577	Silver (Ag)	7440-22-4	82.000	1.293	0.697	6974.590
				Epoxy resin	9003-36-5	10.000	0.158	0.085	850.560
				Diluent	Trade Secret	2.000	0.032	0.017	170.112
				Dicyandiamide	461-58-5	0.900	0.014	0.008	76.550
				Hardener	Trade Secret	5.100	0.080	0.043	433.785
6	Solder	Sn 100	2.900	Sn	7440-31-5	99.987	2.900	1.564	15642.040
				Pb	7439-92-1	0.005	0.000	0.000	0.782
				Cu	7440-50-8	0.003	0.000	0.000	0.469
				Cd	7440-43-9	0.001	0.000	0.000	0.156
				Bi	7440-69-9	0.003	0.000	0.000	0.469
				Sb	7440-36-0	0.001	0.000	0.000	0.156
Total Unit Weight =			185.374						